# **ON Semiconductor**

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**QFET**®

ON Semiconductor

# FQP3N50C/FQPF3N50C 500V N-Channel MOSFET

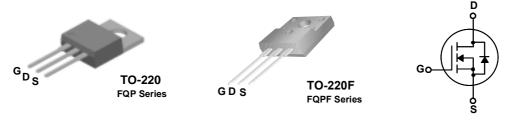
#### **Features**

- 3 A, 500 V,  $R_{DS(on)}$  = 2.5  $\Omega$  @  $V_{GS}$  = 10 V
- Low gate charge (typical 10 nC)
- Low Crss (typical 8.5 pF)
- Fast switching
- · 100 % avalanche tested
- · Improved dv/dt capability

## **Description**

These N-Channel enhancement mode power field effect transistors are produced using ON Semiconductor's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switched mode power supplies, active power factor correction, electronic lamp ballasts based on half bridge topology.



## **Absolute Maximum Ratings**

Symbol		Parameter		FQP3N50C	FQPF3N50C	Units
V <sub>DSS</sub>	Drain-Source V	oltage/		500		V
I <sub>D</sub>	Drain Current	- Continuous (T <sub>C</sub> = 25	5°C)	3	3 *	Α
		- Continuous (T <sub>C</sub> = 10	00°C)	1.8	1.8 *	Α
I <sub>DM</sub>	Drain Current	- Pulsed	(Note 1)	12	12 *	Α
V <sub>GSS</sub>	Gate-Source Vo	oltage		±	± 30	V
E <sub>AS</sub>	Single Pulsed A	Avalanche Energy	(Note 2)	200		mJ
I <sub>AR</sub>	Avalanche Curr	rent	(Note 1)	3		Α
E <sub>AR</sub>	Repetitive Aval	anche Energy	(Note 1)		6.2	mJ
dv/dt	Peak Diode Re	covery dv/dt	(Note 3)		4.5	V/ns
P <sub>D</sub>	Power Dissipat	ion (T <sub>C</sub> = 25°C)		62	25	W
		- Derate above 25°C		0.5	0.2	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and	Storage Temperature Ra	ange	-55 to +150		°C
T <sub>L</sub>	Maximum lead 1/8" from case	temperature for soldering	ng purposes,	300		°C

<sup>\*</sup> Drain current limited by maximum junction temperature

## **Thermal Characteristics**

Symbol	Parameter	FQP3N50C	FQPF3N50C	Units	
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	2.0	4.9	°C/W	
$R_{\theta JS}$	Thermal Resistance, Case-to-Sink Typ.	0.5		°C/W	
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62.5	62.5	°C/W	

# **Package Marking and Ordering Information**

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FQP3N50C	FQP3N50C	TO-220			50
FQPF3N50C	FQPF3N50C	TO-220F			50

# **Electrical Characteristics** T<sub>C</sub> = 25°C unless otherwise noted

ΔβV <sub>DSS</sub>   ATJ   Coefficient   I <sub>D</sub> = 250 μA, Referenced to 25°C     0.7     V   V   V   V   V   V   V   V	Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
ΔBVDsS/ ΔT <sub>J</sub> Breakdown Voltage Temperature Coefficient         I <sub>D</sub> = 250 μA, Referenced to 25°C          0.7          V           IDSS         Zero Gate Voltage Drain Current         V <sub>DS</sub> = 500 V, V <sub>GS</sub> = 0 V           1         1           I <sub>DSSF</sub> Gate-Body Leakage Current, Forward I <sub>GSSR</sub> V <sub>GS</sub> = 30 V, V <sub>DS</sub> = 0 V           100         1           I <sub>GSSR</sub> Gate-Body Leakage Current, Reverse         V <sub>GS</sub> = 30 V, V <sub>DS</sub> = 0 V           -100         1           I <sub>GSSR</sub> Gate-Body Leakage Current, Reverse         V <sub>GS</sub> = 30 V, V <sub>DS</sub> = 0 V           -100         1           I <sub>GSSR</sub> Gate-Body Leakage Current, Reverse         V <sub>GS</sub> = 30 V, V <sub>DS</sub> = 0 V           -100         1           I <sub>GSSR</sub> Gate-Body Leakage Current, Reverse         V <sub>GS</sub> = -30 V, V <sub>DS</sub> = 0 V           -100         1           On Characteristics           V <sub>GS</sub> (n)         Gate Threshold Voltage         V <sub>DS</sub> = 250 µA         2.0          4.0          2.1         2.5          2.1         2.5           2.1         2.5          <	Off Characte	ristics					
ΔTJ   Coefficient	BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	500			V
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $		<b>.</b>	I <sub>D</sub> = 250 μA, Referenced to 25°C		0.7		V/°C
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 500 V, V <sub>GS</sub> = 0 V	-		1	μΑ
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$			V <sub>DS</sub> = 400 V, T <sub>C</sub> = 125°C			10	μΑ
On Characteristics         V <sub>OS</sub> (th)         Gate Threshold Voltage         V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA         2.0          4.0           R <sub>DS</sub> (on)         Static Drain-Source On-Resistance         V <sub>GS</sub> = 10 V, I <sub>D</sub> = 1.5 A          2.1         2.5           g <sub>FS</sub> Forward Transconductance         V <sub>DS</sub> = 40 V, I <sub>D</sub> = 1.5 A         (Note 4)          1.5            Dynamic Characteristics           C <sub>iss</sub> Input Capacitance         V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V, I <sub>D</sub> = 0.0          280         365            C <sub>oss</sub> Output Capacitance         f = 1.0 MHz          50         65            C <sub>oss</sub> Output Capacitance         f = 1.0 MHz          50         65            Switching Characteristics           t <sub>(crs</sub> Reverse Transfer Capacitance           V <sub>DS</sub> = 250 V, I <sub>D</sub> = 3 A, V <sub>D</sub> 10         30            Switching Characteristics           t <sub>(crs</sub> 10         30          25         60          25         60           25         60	I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	V <sub>GS</sub> = 30 V, V <sub>DS</sub> = 0 V			100	nA
$ \begin{array}{c} V_{GS(th)} & \text{Gate Threshold Voltage} & V_{DS} = V_{GS}, I_D = 250 \ \mu\text{A} & 2.0 & & 4.0 \\ \hline R_{DS(on)} & \text{Static Drain-Source} & V_{GS} = 10 \ \text{V}, I_D = 1.5 \ \text{A} & & 2.1 & 2.5 \\ \hline g_{FS} & \text{Forward Transconductance} & V_{DS} = 40 \ \text{V}, I_D = 1.5 \ \text{A} & (\text{Note 4}) & & 1.5 & \\ \hline \\ \textbf{Dynamic Characteristics} & & & & & & & & & & & & & & & & & & &$	I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	V <sub>GS</sub> = -30 V, V <sub>DS</sub> = 0 V			-100	nA
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	On Characte	ristics					
On-Resistance   On-Resistan	V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	2.0		4.0	V
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	R <sub>DS(on)</sub>		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 1.5 A		2.1	2.5	Ω
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 40 V, I <sub>D</sub> = 1.5 A (Note 4)		1.5		S
$ \begin{array}{c} C_{oss} & \text{Output Capacitance} \\ C_{rss} & \text{Reverse Transfer Capacitance} \\ \end{array} \begin{array}{c} f = 1.0 \text{ MHz} \\ \hline \\ C_{rss} & \text{Reverse Transfer Capacitance} \\ \end{array} \begin{array}{c}$	Dynamic Cha	aracteristics					
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	C <sub>iss</sub>	Input Capacitance			280	365	pF
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	C <sub>oss</sub>	Output Capacitance	T = 1.0 MHZ		50	65	pF
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	C <sub>rss</sub>	Reverse Transfer Capacitance			8.5	11	pF
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	Switching Ch	naracteristics					
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	t <sub>d(on)</sub>	Turn-On Delay Time			10	30	ns
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	t <sub>r</sub>	Turn-On Rise Time			25	60	ns
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	t <sub>d(off)</sub>	Turn-Off Delay Time			35	80	ns
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	t <sub>f</sub>	Turn-Off Fall Time	(Note 4, 5)		25	60	ns
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> = 400 V, I <sub>D</sub> = 3 A,		10	13	nC
Drain-Source Diode Characteristics and Maximum Ratings $I_S$ Maximum Continuous Drain-Source Diode Forward Current       3 $I_{SM}$ Maximum Pulsed Drain-Source Diode Forward Current       12 $V_{SD}$ Drain-Source Diode Forward Voltage $V_{GS} = 0 \text{ V}, I_S = 3 \text{ A}$ 1.4 $t_{rr}$ Reverse Recovery Time $V_{GS} = 0 \text{ V}, I_S = 3 \text{ A},$ 170 $dI_E / dt = 100 \text{ A/us}$ (Note 4)	Q <sub>gs</sub>	Gate-Source Charge	V <sub>GS</sub> = 10 V		1.5		nC
$I_S$ Maximum Continuous Drain-Source Diode Forward Current       3 $I_{SM}$ Maximum Pulsed Drain-Source Diode Forward Current       12 $V_{SD}$ Drain-Source Diode Forward Voltage $V_{GS} = 0 \text{ V}, I_S = 3 \text{ A}$ 1.4 $t_{rr}$ Reverse Recovery Time $V_{GS} = 0 \text{ V}, I_S = 3 \text{ A},$ 170 $dI_E / dt = 100 \text{ A/us}$ (Note 4)	$Q_{gd}$	Gate-Drain Charge	(Note 4, 5)		5.5		nC
$I_{SM}$ Maximum Pulsed Drain-Source Diode Forward Current 12 $V_{SD}$ Drain-Source Diode Forward Voltage $V_{GS} = 0 \text{ V}, I_S = 3 \text{ A}$ 1.4 $t_{rr}$ Reverse Recovery Time $V_{GS} = 0 \text{ V}, I_S = 3 \text{ A}, I_{SD} = 3 \text{ A}$ 170 1	Drain-Source	Diode Characteristics and Maximum R	atings				
$V_{SD}$ Drain-Source Diode Forward Voltage $V_{GS} = 0 \text{ V}, I_S = 3 \text{ A}$ 1.4 $t_{rr}$ Reverse Recovery Time $V_{GS} = 0 \text{ V}, I_S = 3 \text{ A},$ 170	I <sub>S</sub>	Maximum Continuous Drain-Source Dio	de Forward Current			3	Α
$t_{rr}$ Reverse Recovery Time $V_{GS} = 0 \text{ V, } I_S = 3 \text{ A,}$ 170 $dI_E / dt = 100 \text{ A/us}$ (Note 4)	I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode F	orward Current			12	Α
$d_{\rm F}/dt = 100 \text{ A/us}$ (Note 4)	V <sub>SD</sub>	Drain-Source Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 3 A	-		1.4	V
$Q_{rr}$ Reverse Recovery Charge $dI_F / dt = 100 \text{ A/}\mu\text{s}$ (Note 4) 0.7 !	t <sub>rr</sub>	Reverse Recovery Time			170		ns
	Q <sub>rr</sub>	Reverse Recovery Charge	$dI_F / dt = 100 A/\mu s$ (Note 4)		0.7		μС

- 1. Repetitive Rating : Pulse width limited by maximum junction temperature
- 2. L = 40mH, I $_{AS}$  = 3A, V $_{DD}$  = 50V, R $_{G}$  = 25  $\Omega$ , Starting T $_{J}$  = 25°C
- 3.  $I_{SD} \le 3A$ , di/dt  $\le 200A/\mu s$ ,  $V_{DD} \le BV_{DSS}$ , Starting  $T_J$  = 25°C
- 4. Pulse Test : Pulse width  $\leq 300 \mu s, \ Duty \ cycle \leq 2\%$
- 5. Essentially independent of operating temperature

# **Typical Performance Characteristics**

Figure 1. On-Region Characteristics

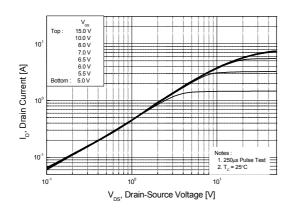


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

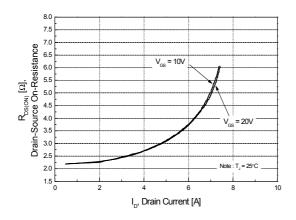


Figure 5. Capacitance Characteristics

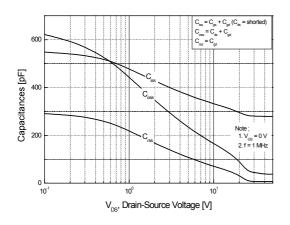


Figure 2. Transfer Characteristics

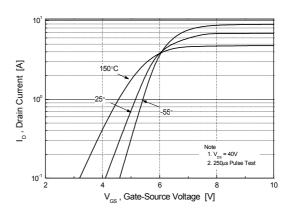


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperatue

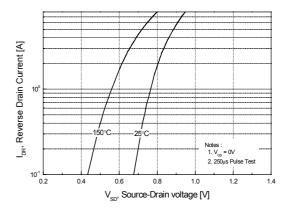
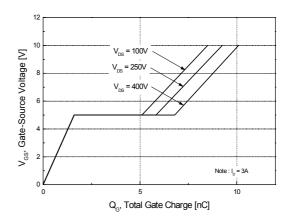


Figure 6. Gate Charge Characteristics



# **Typical Performance Characteristics** (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

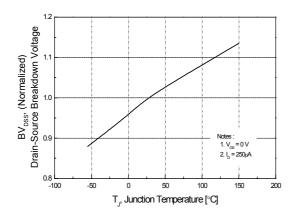


Figure 9-1. Maximum Safe Operating Area of FQP3N50C

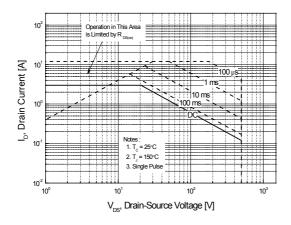


Figure 10. Maximum Drain Current

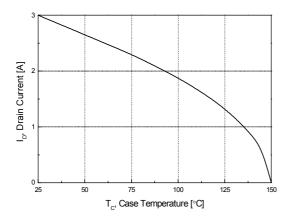


Figure 8. On-Resistance Variation vs. Temperature

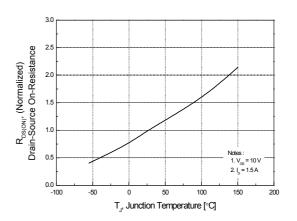
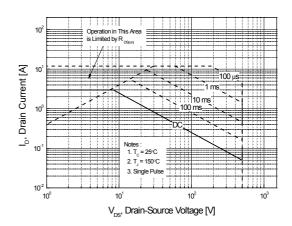


Figure 9-2. Maximum Safe Operating Area of FQPF3N50C



# Typical Performance Characteristics (Continued)

Figure 11-1. ransient Thermal Response Curve of FQP3N50C

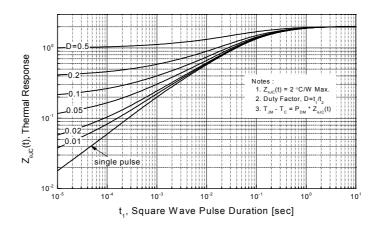
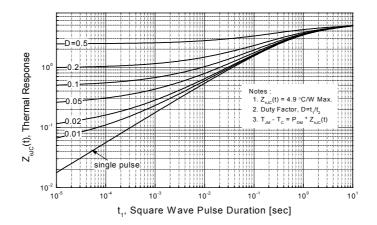
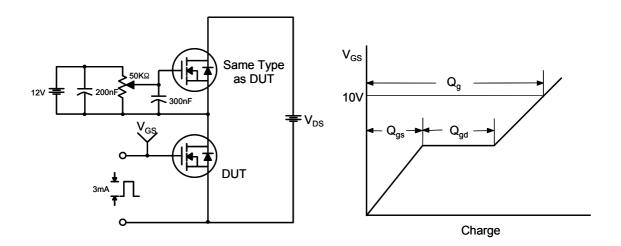


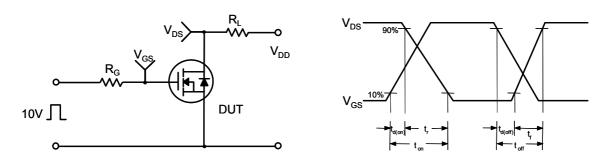
Figure 11-2. ransient Thermal Response Curve of FQPF3N50C



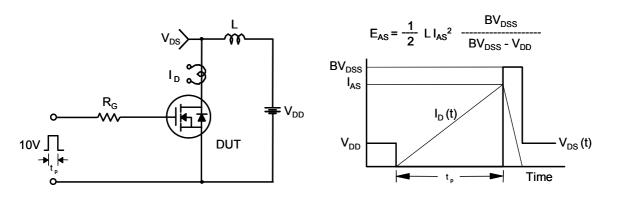
## **Gate Charge Test Circuit & Waveform**



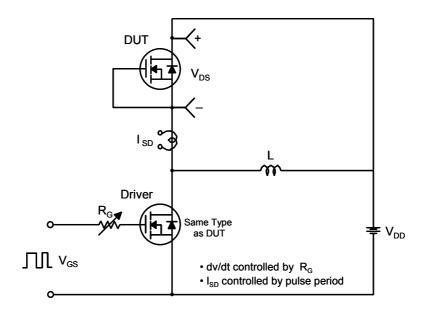
## **Resistive Switching Test Circuit & Waveforms**

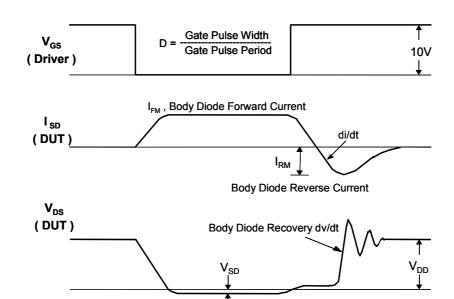


## **Unclamped Inductive Switching Test Circuit & Waveforms**



## Peak Diode Recovery dv/dt Test Circuit & Waveforms

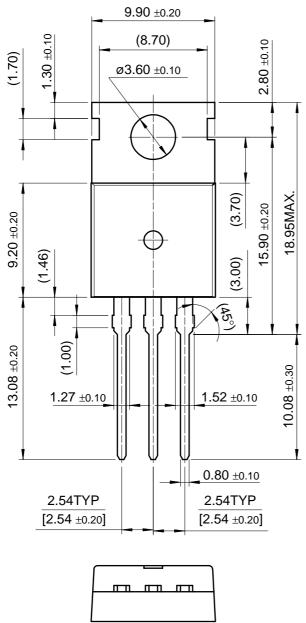


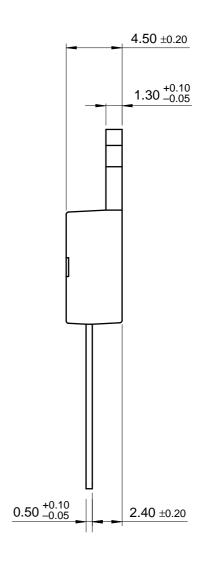


**Body Diode** Forward Voltage Drop

## **Mechanical Dimensions**

TO-220



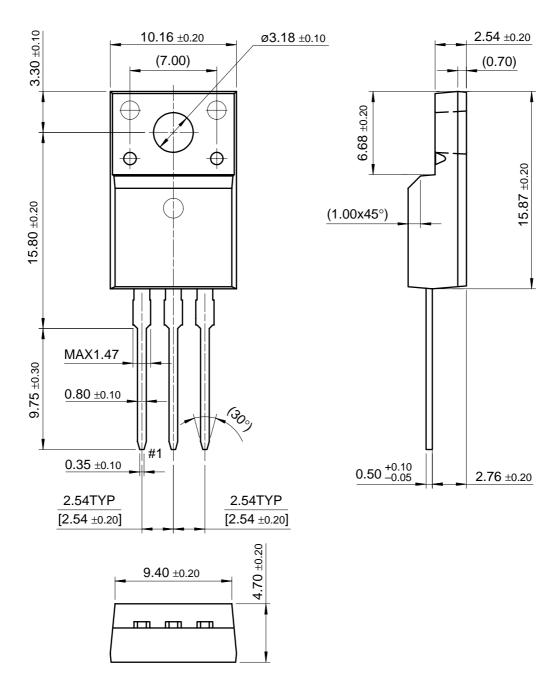




Dimensions in Millimeters

# **Mechanical Dimensions** (Continued)

# TO-220F



Dimensions in Millimeters

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